

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ming-Daou Lee</td> <td>08/19/2008</td> </tr> <tr> <td>Erh-Kun Lai</td> <td>08/19/2008</td> </tr> <tr> <td>Kuang-Yeh Hsieh</td> <td>08/25/2008</td> </tr> </tbody> </table>		Name	Execution Date	Ming-Daou Lee	08/19/2008	Erh-Kun Lai	08/19/2008	Kuang-Yeh Hsieh	08/25/2008
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Ming-Daou Lee	08/19/2008								
Erh-Kun Lai	08/19/2008								
Kuang-Yeh Hsieh	08/25/2008								
RECEIVING PARTY DATA									
Name:	Macronix International Co., Ltd.								
Street Address:	No. 16 Li-Hsin Road								
Internal Address:	Science-Based Industrial Park								
City:	Hsinchu								
State/Country:	TAIWAN								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12204515</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12204515				
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CORRESPONDENCE DATA									
Fax Number:	(650)712-0263								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	6507120340								
Email:	kmarley@hmbay.com								
Correspondent Name:	Mark Haynes								
Address Line 1:	P.O. Box 366								
Address Line 2:	Haynes Beffel & Wolfeld LLP								
Address Line 4:	Half Moon Bay, CALIFORNIA 94019								
ATTORNEY DOCKET NUMBER:	MXIC 1843-1								
NAME OF SUBMITTER:	Mark A. Haynes								

Total Attachments: 3
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**PATENT
 REEL: 021507 FRAME: 0044**

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MXIC 1843-1
(P960103US)

**JOINT TO CORPORATE
ASSIGNMENT**

WHEREAS, the undersigned,

- | | |
|--|---|
| <p>(1) Ming-Daou Lee
No. 101, Yong-an St.
Chiayi City, 600 Taiwan R.O.C.</p> | <p>(2) Erh-Kun Lai
No. 14, Lane 411,
Youyuan N. Rd.
Longjing Shiang, Taichung
County 434 Taiwan, R.O.C.</p> |
| <p>(3) Kuang-Yeu Hsieh
No. 16, Lising Rd.
Hsinchu City, 300
Taiwan, R.O.C.</p> | |

hereinafter termed "Inventors", have invented certain new and useful improvements in

HIGH DENSITY RESISTANCE BASED SEMICONDUCTOR DEVICE

and have filed an application for a United States patent disclosing and identifying the above invention on 04 SEP 2008 as Application No. 12/204,515, OR are filing such an application herewith, and have executed an oath or declaration of inventorship for such non-provisional application on:

- (1) the 19TH day of AUGUST, 2008;
- (2) the 19TH day of AUGUST, 2008;
- (3) the 22ND day of AUGUST, 2008.

(hereinafter termed "applications"); and

WHEREAS, Macronix International Co., Ltd., a corporation of Taiwan, having a place of business at No. 16, Li-Hsin Road, Science-Based Industrial Park, Hsinchu, Taiwan R.O.C. (hereinafter termed "Assignee"), is desirous of acquiring the entire right, title and interest in and to said applications and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered by said Inventor (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventors to have been received in full from said Assignee:

1. Said Inventors do hereby sell, assign, transfer and convey unto said Assignee the entire right, title and interest (a) in and to said applications and said invention; (b) in and to all

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rights to apply for foreign patents on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extensions of any of said patents.

2. Said Inventors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and foreign countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (d) for filing and prosecuting applications for reissuance of any said patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventor in providing such cooperation shall be paid for by said Assignee.

3. The terms and covenants of this assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventors, the inventors' respective heirs, legal representatives and assigns.

4. Said Inventors hereby warrant and represent that said inventors have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

5. Said Inventors hereby authorize any of the following attorneys: Mark A. Haynes, Ernest J. Beffel, Jr., Warren S. Wolfeld, James F. Hann, Bill Kennedy, Kenta Suzue to (a) insert the date of execution of the oath or declaration of inventorship, and (b) insert the application number and filing date of this application when known.

IN WITNESS WHEREOF, said Inventors have executed and delivered this instrument to said Assignee as of the date written below.

MING-DAOU LEE 李明道
ERH-KUN LAI 賴二崑

Date: _____

Date: Aug. 19. 2008

ERH-KUN LAI 賴二崑

Date: _____

KUANG-YEU HSIEH 謝光宇

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rights to apply for foreign patents on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extensions of any of said patents.

2. Said Inventors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and foreign countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (d) for filing and prosecuting applications for reissuance of any said patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventor in providing such cooperation shall be paid for by said Assignee.

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IN WITNESS WHEREOF, said Inventors have executed and delivered this instrument to said Assignee as of the date written below.

Ming-Daou Lee
MING-DAOU LEE 李明道

Date: 2008, 8, 19

ERH-KUNG LAL 賴三現
KUANG-YEH/HSIEH 謝光宇

Date: _____

Date: 2008, 8, 25